



Product / Package Information	
Package	LGA_CAV
Body Size (mm)	3.35 X 2.5 X 0.98
Ball Count	3
Terminal Finish	Gold

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Lid/Shield								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Stainless steel	Iron	7439-89-6	4.61 E-03	68.84	688400	23.69		236865
Stainless steel	Chromium	7440-47-3	1.16 E-03	17.31	173057	5.95		59546
Stainless steel	Nickel	7440-02-0	5.19 E-04	7.74	77400	2.66		26632
Stainless steel	Manganese	7439-96-5	8.15 E-05	1.22	12160	0.42		4184
Stainless steel	Silicon	7440-21-3	3.33 E-05	0.50	4972	0.17		1711
Stainless steel	Carbon	7440-44-0	3.14 E-06	0.05	468	0.02		161
Stainless steel	Phosphorus	7723-14-0	1.47 E-06	0.02	220	0.01		76
Stainless steel	Sulfur	7704-34-9	1.28 E-07	0.002	19	0.001		7
Tin & its alloys	Tin	7440-31-5	2.90 E-04	4.33	43274	1.49		14890
Subtotal			6.70 E-03	100.0	999970	34.41		344071

Laminate								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Composite	Laminate core	Proprietary	3.20 E-03	28.90	289000	16.42		164198
Copper & its alloys	Copper	7440-50-8	1.10 E-03	9.93	99300	5.64		56418
Other organic materials	Solder Mask	Proprietary	4.01 E-04	3.63	36280	2.06		20613
Nickel & its alloys	Nickel	7440-02-0	1.87 E-03	16.88	168782	9.59		95895
Precious Metals	Gold	7440-57-5	7.36 E-05	0.67	6656	0.38		3782
Passives 1	Copper Foil	7440-50-8	2.00 E-03	18.12	181200	10.30		102950
Passives 1	Barium Titanate	12047-27-7	1.33 E-04	1.20	12000	0.68		6818
Passives 1	Epoxy-based polymer	Proprietary	2.88 E-05	0.26	2600	0.15		1477
Passives 1	Proprietary organic dispersant	Proprietary	3.32 E-05	0.30	3000	0.17		1704
Passives 1	Halogen-free curative	Proprietary	1.33 E-05	0.12	1200	0.07		682
Passives 2	Copper	7440-50-8	2.20 E-03	19.92	199200	11.32		113177
Passives 2	Zinc	7440-66-6	7.78 E-06	0.07	703	0.04		399
Passives 2	Arsenic	7440-38-2	8.85 E-07	0.01	80	0.005		45
Passives 2	Chromium	7440-47-3	1.77 E-07	0.002	16	0.001		9
Passives 2	Lead	7439-92-1	8.85 E-09	0.0001	1	0.00005		0
Passives 2	Nickel	7440-02-0	4.43 E-09	0.00004	0	0.00002		0
Subtotal			1.11 E-02	100.00	1000000	56.82		568167

Solder Land								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Copper & its alloys	Copper	7440-50-8	2.00 E-04	76.92	769231	1.03		10271
Nickel & its alloys	Nickel	7440-02-0	5.00 E-05	19.23	192308	0.26		2568
Precious Metals	Gold	7440-57-5	1.00 E-05	3.85	38462	0.05		514
Subtotal			2.60 E-04	100.00	1000000	1.34		13352

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Gold	7440-57-5	4.84 E-05	99	990000	0.25		2486
Precious metals	Palladium	7440-05-3	4.89 E-07	1	10000	0.003		25
Subtotal			4.89 E-05	100	1000000	0.25		2511

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.00 E-04	100	1000000	3.59		35949

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Silver	7440-22-4	2.25 E-04	75.00	750000	1.16		11555
Other organic materials	Bisphenol F type epoxy resin	9003-36-5	3.00 E-05	10.00	100000	0.15		1541
Other organic materials	Bisphenol A type epoxy resin	25068-38-6	3.00 E-05	10.00	100000	0.15		1541
Others	Additives	Proprietary	9.00 E-06	3.00	30000	0.05		462
Others	Curing Agent	Proprietary	6.00 E-06	2.00	20000	0.03		308
Subtotal			3.00 E-04	100.00	1000000	1.54		15407

Die Coat								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Other organic materials	Polydimethylsiloxane	Proprietary	2.00 E-04	100	1000000	1.03		10271

Lid/ Shield Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Silver	7440-22-4	1.50 E-04	75.0	750000	0.77		7703
Other organic materials	Bisphenol F type epoxy resin	9003-36-5	2.00 E-05	10.0	100000	0.10		1027
Other organic materials	Bisphenol A type epoxy resin	25068-38-6	2.00 E-05	10.0	100000	0.10		1027
Others	Additives	Proprietary	6.00 E-06	3.0	30000	0.03		308
Others	Curing Agent	Proprietary	4.00 E-06	2.0	20000	0.02		205
Subtotal			2.00 E-04	100.00	1000000	1.03		10271

Package Totals	Weight (g)	Percentage (%)	PPM
	1.95 E-02	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.

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